

What is claimed is:

1. An apparatus for manufacturing semiconductor device comprising:

5 an enclosing structure defining a closed space isolated from an external environment;

 a purifying system for keeping atmosphere in the closed space clean;

10 a processing device disposed in said closed space for processing a semiconductor wafer; and

 a pressure elevating device for keeping an internal pressure high in said closed space so as to be higher than a pressure in said external environment.

15 2. An apparatus according to claim 1, wherein said enclosing structure comprises a housing.

 3. An apparatus according to claim 1, wherein said purifying system comprises a filter unit mounted on
20 said enclosing structure for supplying clean air into said closed space.

 4. An apparatus according to claim 3, wherein
 said pressure elevating device comprises a fan disposed in
25 said filter unit and a damper for adjusting a rate of air discharged from said closed space.

5. An apparatus according to claim 1, wherein
said apparatus comprises a polishing apparatus for polishing
a semiconductor wafer.

5 6. An apparatus according to claim 5, said
polishing apparatus comprising:

 a polishing section for polishing a semiconductor
wafer; and

10 a cleaning section for cleaning a polished
semiconductor wafer;

 wherein an internal pressure in said cleaning
section is higher than an internal pressure in said
polishing section.

15 7. An apparatus according to claim 6, further
comprising a loading/unloading section for receipt of a
semiconductor wafer to be polished and a polished
semiconductor wafer;

20 wherein an internal pressure in said
loading/unloading section is higher than said internal
pressure in said cleaning section.

25 8. An apparatus according to claim 6, further
comprising a partition having an opening for partitioning
said cleaning section from said polishing section.